

PLATING METHOD

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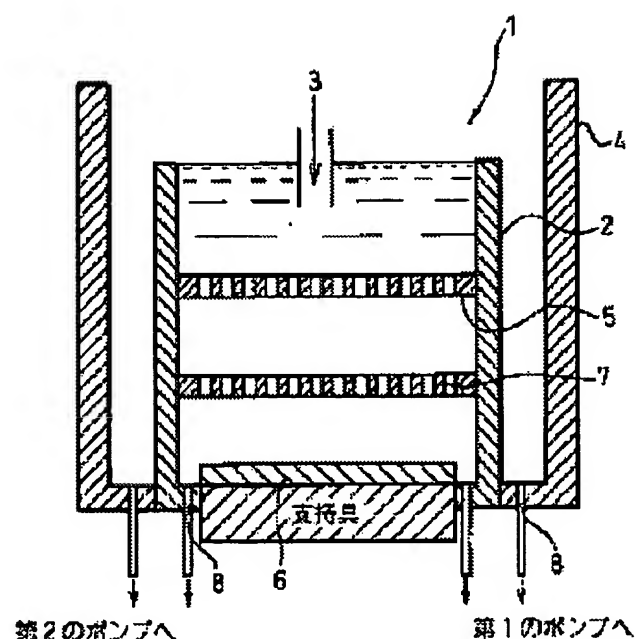
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Abstract of JP2000017480

PROBLEM TO BE SOLVED: To provide the plating method by which precision plating is attained by the use of a jet plater.

SOLUTION: A plating soln. 3 is jetted downward through an anode, and a material 6 to be plated arranged at the lower part of a plating tank 1 is electroplated. The plating tank 1 is composed of two tanks, and the plating soln. is supplied from the upper part of the inner first tank and discharged from the bottom to plate the material. A fixed amt. of the plating soln. is kept in the first tank at all times, the excess plating soln. overflows the first tank and flows into the outer second tank, and the charge and discharge of the plating soln. is controlled.



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